

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1018csw#trpbf

(Engineering Calculation)

SOIC WIDE

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**TOTAL MASS (g) : 0.246927**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002640	1000000	10691.4033203		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.138021	975000	558953.875		
		Iron (Fe)	7439-89-6	0.003397	24000	13757.0820312		
		Phosphorus (P)	7723-14-0	0.000042	300	170.090499878		
		Zinc (Zn)	7440-66-6	0.000099	700	400.927612305		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.141559</b>	<b>1000000</b>	<b>573281.9375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.004771	1000000	19322.9609375		
		<b>External Plating Total:</b>				<b>0.004771</b>	<b>1000000</b>	<b>19322.9609375</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001132	1000000	4584.34423828		
<b>Internal Plating Total:</b>				<b>0.001132</b>	<b>1000000</b>	<b>4584.34423828</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000841	750000	3405.85986328		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000280	250000	1133.93664551		
<b>Die Attach Total:</b>				<b>0.001121</b>	<b>1000000</b>	<b>4539.79638672</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.009816	103000	39752.5820312		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.085294	895000	345421.40625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000191	2000	773.506835938		
		<b>Encapsulation Total:</b>				<b>0.095301</b>	<b>1000000</b>	<b>385947.53125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000403	1000000	1632.05883789		
					<b>TOTAL MASS (g) :</b>	<b>0.246927</b>		